

15A, 60V, 0.065 Ohm, ESD Rated, Logic Level, N-Channel Power MOSFETs

These are N-Channel power MOSFETs manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI circuits, gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers, and relay drivers. These transistors can be operated directly from integrated circuits.

Formerly developmental type TA49165.

Ordering Information

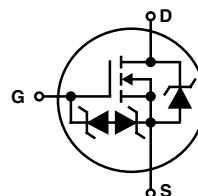
PART NUMBER	PACKAGE	BRAND
RFD15N06LE	TO-251AA	F15N6L
RFD15N06LESM	TO-252AA	F15N6L

NOTE: When ordering, use the entire part number. For ordering in tape and reel, add the suffix 9A to the part number, i.e. RFD15N06LESM9A.

Features

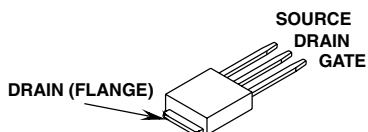
- 15A, 60V
- $r_{DS(ON)} = 0.065\Omega$
- 2kV ESD Protected
- Temperature Compensating PSPICE® Model
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- 175°C Operating Temperature
- Related Literature
 - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol

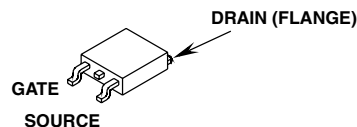


Packaging

JEDEC TO-251AA



JEDEC TO-252AA



RFD15N06LE, RFD15N06LESM

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

	RFD15N06LE, RFD15N06LESM	UNITS
Drain to Source Voltage (Note 1)	V_{DSS}	60 V
Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1)	V_{DGR}	60 V
Gate to Source Voltage	V_{GS}	± 10 V
Continuous Drain Current	I_D	15 A
Pulsed Drain Current (Note 3)	I_{DM}	Refer to Peak Current Curve
Pulsed Avalanche Rating	E_{AS}	Refer to UIS Curve
Power Dissipation	P_D	72 W
Derate above 25°C		0.48 W/ $^\circ\text{C}$
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175 $^\circ\text{C}$
Electrostatic Discharge Rating MIL-STD-883, Category B(2)	ESD	2 kV
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s.	T_L	300 $^\circ\text{C}$
Package Body for 10s, See Techbrief 334	T_{pkg}	260 $^\circ\text{C}$

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^\circ\text{C}$ to 150°C .

Electrical Specifications $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V, Figure 13		60	-	-	V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250μA, Figure 12		1	-	2	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 48V, V _{GS} = 0V	T _C = 25°C	-	-	1	μA
			T _C = 150°C	-	-	50	μA
Gate to Source Leakage Current	I _{GSS}	V _{GS} = ±10V		-	-	10	μA
Drain to Source On Resistance	r _{DS(ON)}	I _D = 15A, V _{GS} = 5V		-	-	0.065	Ω
Turn-On Time	t _{ON}	V _{DD} = 30V, I _D = 15A, R _L = 2.0Ω, V _{GS} = 5V, R _{GS} = 2.5Ω Figures 10, 18, 19		-	-	77	ns
Turn-On Delay Time	t _{d(ON)}			-	11	-	ns
Rise Time	t _r			-	40	-	ns
Turn-Off Delay Time	t _{d(OFF)}			-	30	-	ns
Fall Time	t _f			-	18	-	ns
Turn-Off Time	t _{OFF}			-	-	75	ns
Total Gate Charge	Q _{g(TOT)}	V _{GS} = 0V to 10V	V _{DD} = 48V, I _D = 15A, R _L = 3.20Ω Figures 20, 21	-	39	49	nC
Gate Charge at 5V	Q _{g(5)}	V _{GS} = 0V to 5V		-	21	26	nC
Threshold Gate Charge	Q _{g(TH)}	V _{GS} = 0V to 1V		-	0.95	1.20	nC
Input Capacitance	C _{ISS}	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz Figure 14		-	855	-	pF
Output Capacitance	C _{OSS}			-	240	-	pF
Reverse Transfer Capacitance	C _{RSS}			-	75	-	pF
Thermal Resistance Junction to Case	R _{θJC}			-	-	2.08	°C/W
Thermal Resistance Junction to Ambient	R _{θJA}	TO-251 and TO-252		-	-	100	°C/W

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	$I_{SD} = 15\text{A}$	-	-	1.5	V
Diode Reverse Recovery Time	t_{rr}	$I_{SD} = 15\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	80	ns

NOTES:

2. Pulse Test: Pulse Width $\leq 300\text{ms}$, Duty Cycle $\leq 2\%$.
3. Repetitive Rating: Pulse Width limited by max junction temperature. See Transient Thermal Impedance Curve (Figure 3) and Peak Current Capability Curve (Figure 5).

Typical Performance Curves Unless Otherwise Specified

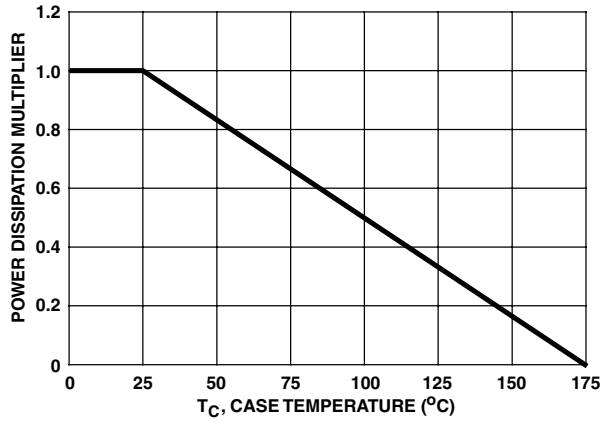


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

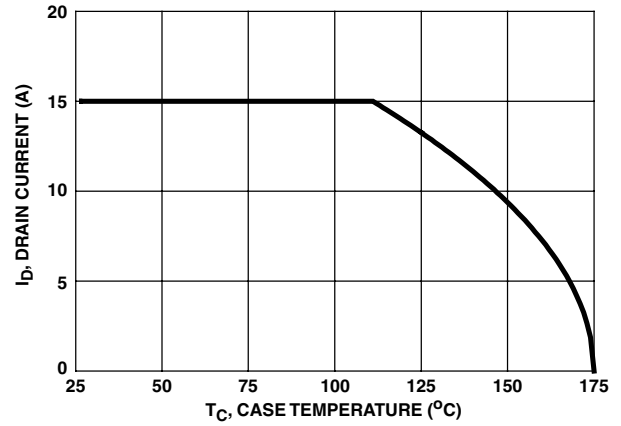


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

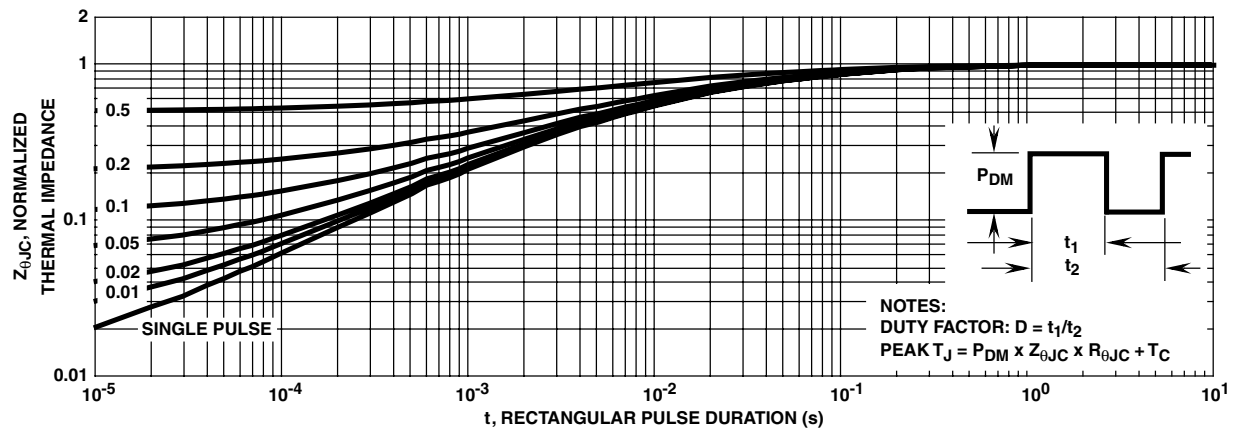


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

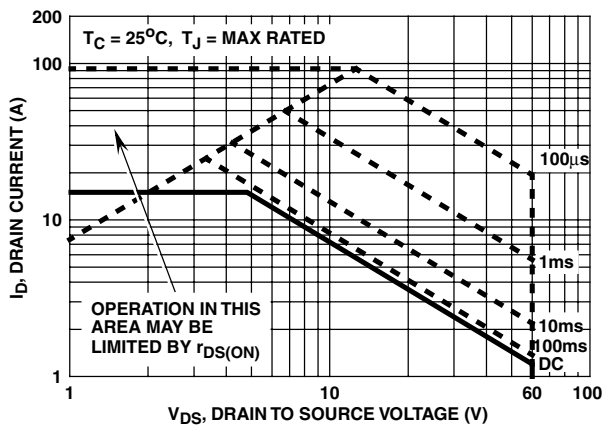


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

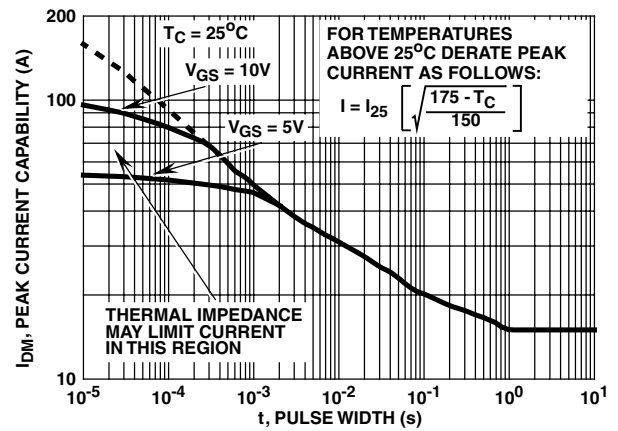
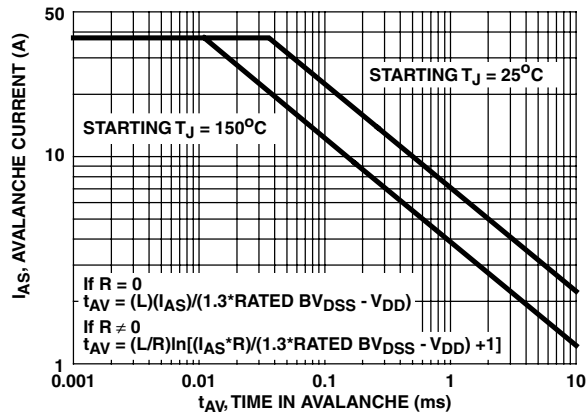


FIGURE 5. PEAK CURRENT CAPABILITY

Typical Performance Curves Unless Otherwise Specified (Continued)



NOTE: Refer to Intersil Application Notes AN9321 and AN9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING

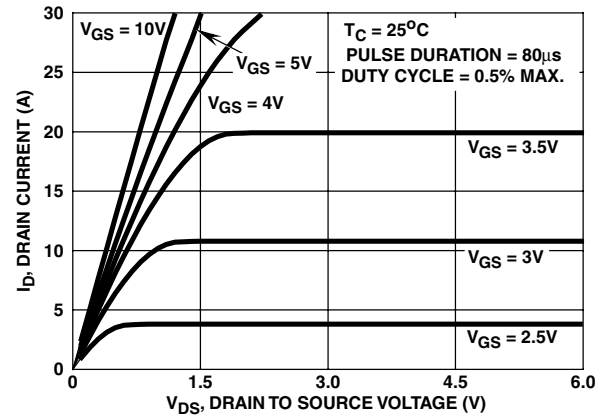


FIGURE 7. SATURATION CHARACTERISTICS

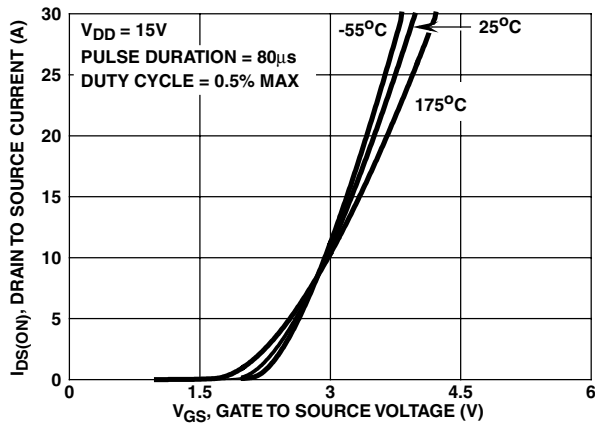


FIGURE 8. TRANSFER CHARACTERISTICS

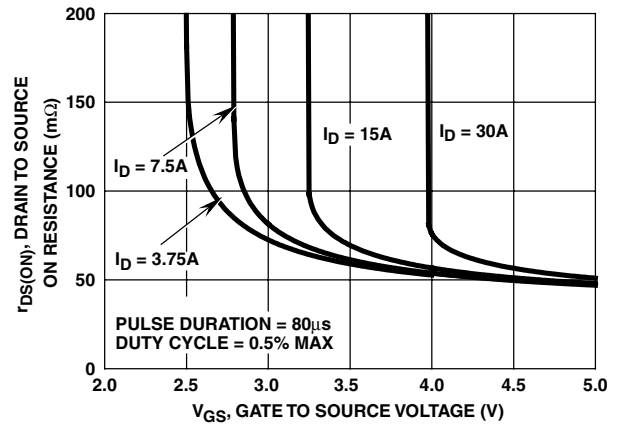


FIGURE 9. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

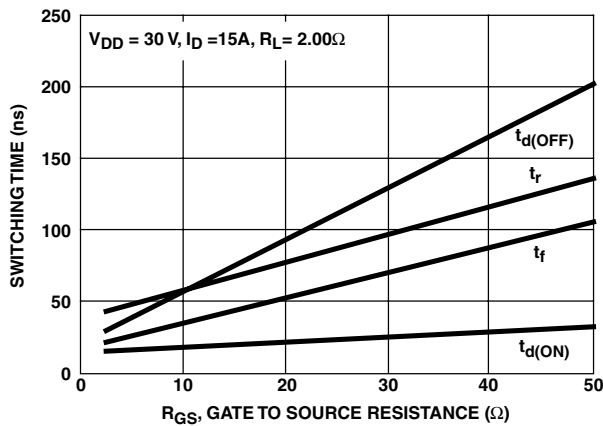


FIGURE 10. SWITCHING TIME vs GATE RESISTANCE

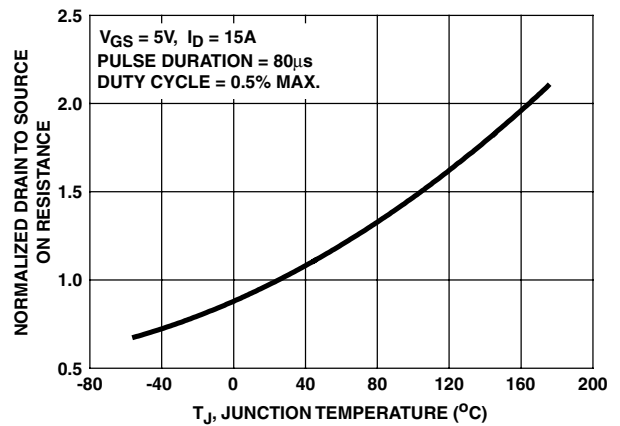


FIGURE 11. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

Typical Performance Curves Unless Otherwise Specified (Continued)

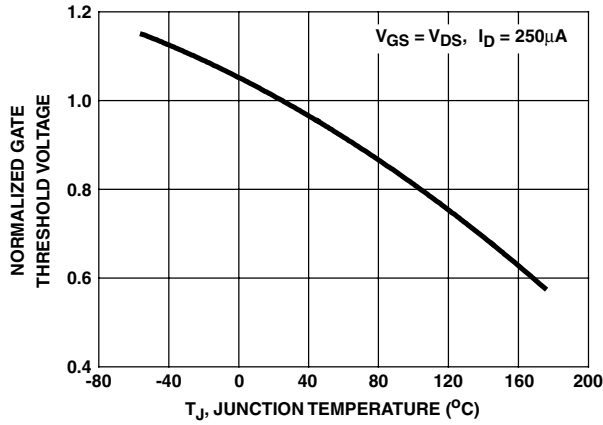


FIGURE 12. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

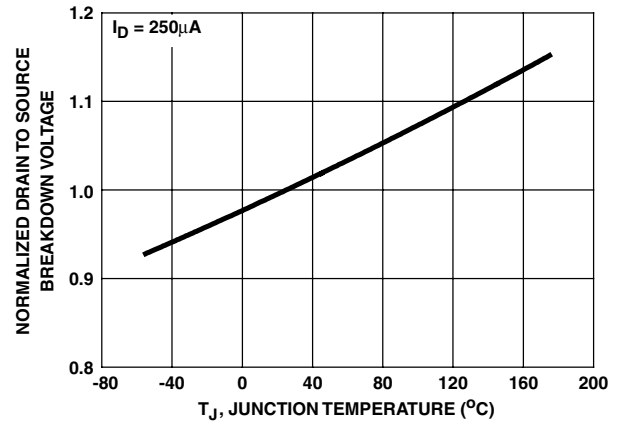


FIGURE 13. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

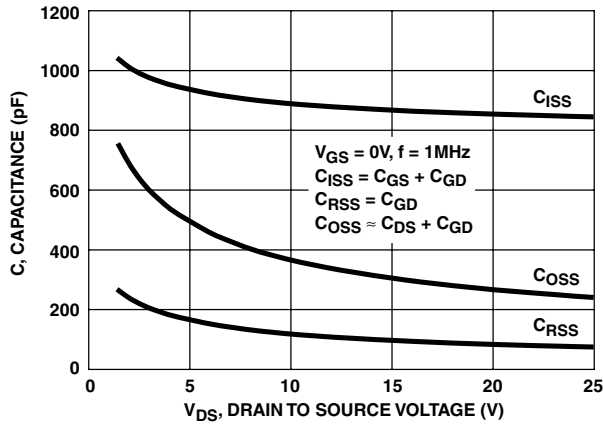
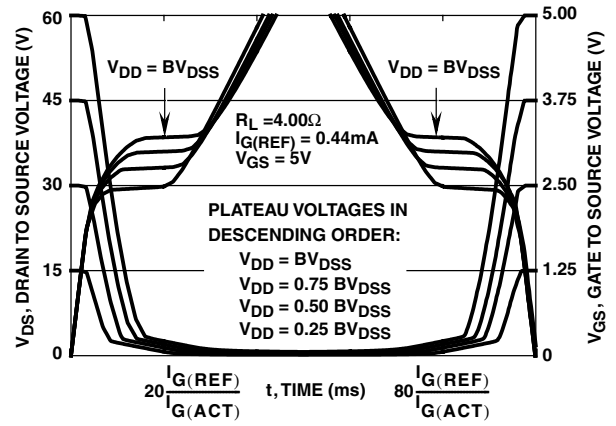


FIGURE 14. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Intersil Application Notes AN7254 and AN7260.

FIGURE 15. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

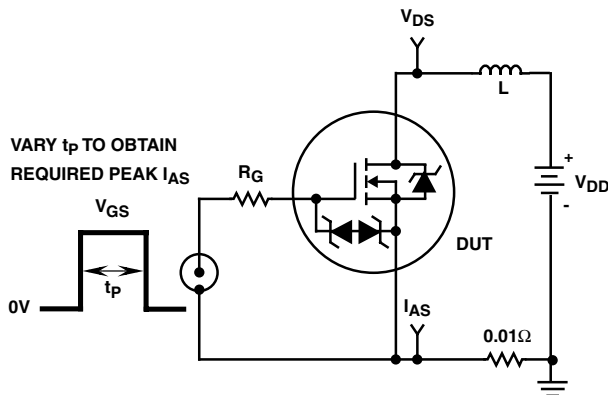


FIGURE 16. UNCLAMPED ENERGY TEST CIRCUIT

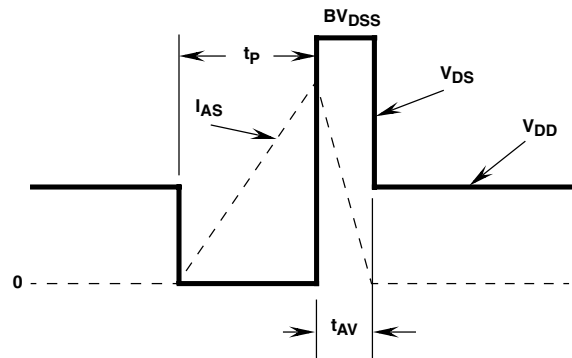


FIGURE 17. UNCLAMPED ENERGY WAVEFORMS

Test Circuits and Waveforms (Continued)

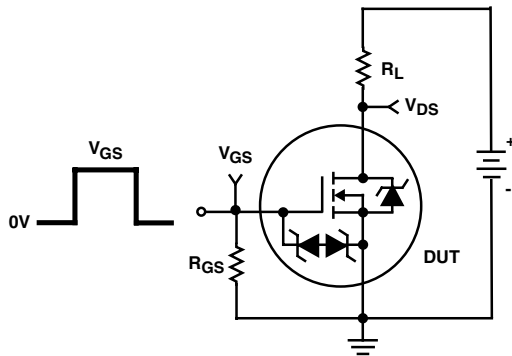


FIGURE 18. SWITCHING TIME TEST CIRCUIT

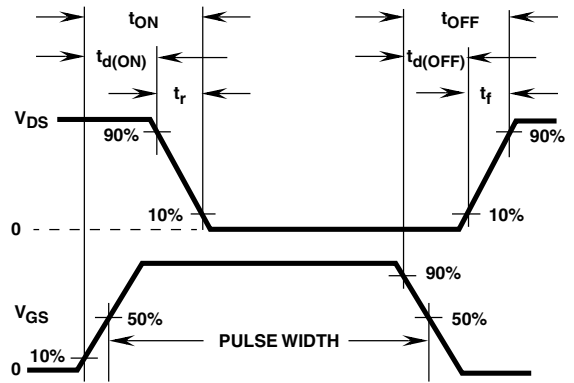


FIGURE 19. RESISTIVE SWITCHING WAVEFORMS

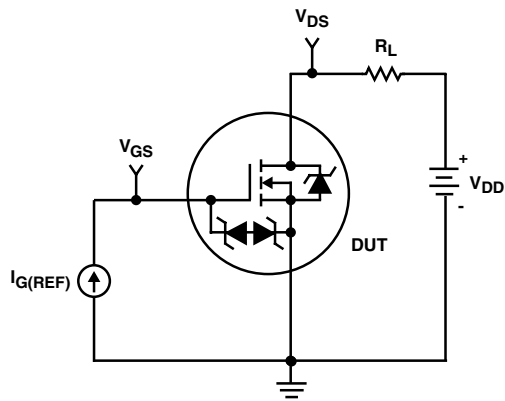


FIGURE 20. GATE CHARGE TEST CIRCUIT

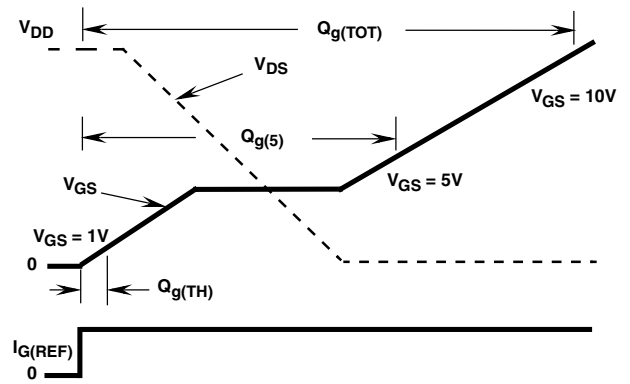


FIGURE 21. GATE CHARGE WAVEFORMS

RFD15N06LE, RFD15N06LESM

PSPICE Electrical Model

SUBCKT RFD15N06LE 2 1 3 ; rev 5/13/95

CA 12 8 2.50e-9
CB 15 14 2.4e-9
CIN 6 8 7.70e-10

DBODY 7 5 DBODYMOD
DBREAK 5 11 DBREAKMOD
DESD1 91 9 DESD1MOD
DESD2 91 7 DESD2MOD
DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 65.18
EDS 14 8 5 8 1
EGS 13 8 6 8 1
ESG 6 10 6 8 1
EVTHRES 6 21 19 8 1
EVTEMP 20 6 18 22 1

IT 8 17 1

LDRAIN 2 5 1e-9
LGATE 1 9 2.77e-9
LSOURCE 3 7 2.98e-9

MMED 16 6 8 8 MMEDMOD
MSTRO 16 6 8 8 MSTROMOD
MWEAK 16 21 8 8 MWEAKMOD

RBREAK 17 18 RBREAKMOD 1
RDRAIN 50 16 RDRAINMOD 14.52e-3
RGATE 9 20 2.6
RLDRAIN 2 5 10
RLGATE 1 9 27.7
RLSOURCE 3 7 29.8
RSLC1 5 51 RSLCMOD 1e-6
RSLC2 5 50 1e3
RSOURCE 8 7 RSOURCEMOD 20.05e-3
RVTHRES 22 8 RVTHRESMOD 1
RVTEMP 18 19 RVTEMPMOD 1

S1A 6 12 13 8 S1AMOD
S1B 13 12 13 8 S1BMOD
S2A 6 15 14 13 S2AMOD
S2B 13 15 14 13 S2BMOD

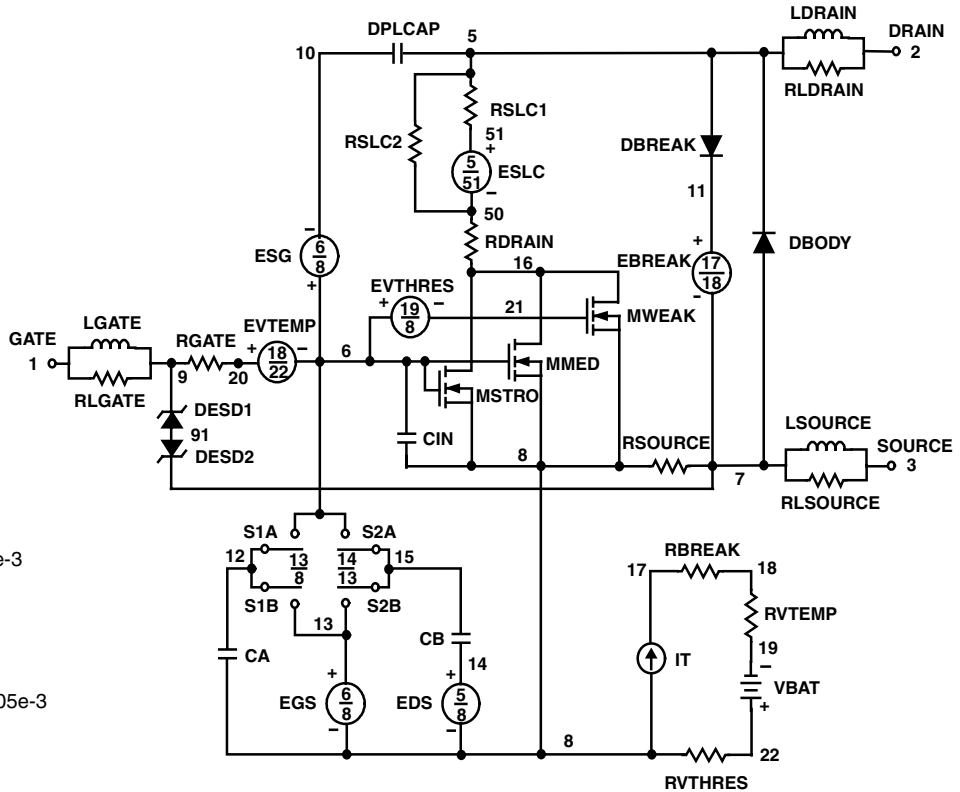
VBAT 22 19 DC 1

ESLC 51 50 VALUE = {(V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)/(1e-6*72),5))}

.MODEL DBODYMOD D (IS = 6.5e-13 RS = 1.20e-2 TRS1 = 1.75e-3 TRS2 = 5.08e-6 CJO = 7.45e-10 TT = 4.61e-8 M = 0.46)
.MODEL DBREAKMOD D (RS = 1.28e-1 TRS1 = -2.15e-3 TRS2 = 1.05e-5)
.MODEL DESD1MOD D (BV = 12.7 TBV1 = 0 TBV2 = 0 RS = 35 TRS1 = 1.2e-6 TRS2 = 0)
.MODEL DESD2MOD D (BV = 12.7 TBV1 = 0 TBV2 = 0 RS = 0 TRS1 = 0 TRS2 = 0)
.MODEL DPLCAPMOD D (CJO = 4.32e-10 IS = 1e-30 N = 10 M = 0.54)
.MODEL MMEDMOD NMOS (VTO = 1.60 KP = 1.75 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 2.60)
.MODEL MSTROMOD NMOS (VTO = 1.93 KP = 26.0 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u)
.MODEL MWEAKMOD NMOS (VTO = 1.39 KP = 0.09 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 26.0 RS = 0.1)
.MODEL RBREAKMOD RES (TC1 = 9.76e-4 TC2 = 5.11e-7)
.MODEL RDRAINMOD RES (TC1 = 1.30e-2 TC2 = 4.49e-5)
.MODEL RSLCMOD RES (TC1 = 3.00e-3 TC2 = 6.00e-6)
.MODEL RSOURCEMOD RES (TC1 = 0 TC2 = 0)
.MODEL RVTHRESMOD RES (TC1 = -1.43e-3 TC2 = -6.72e-6)
.MODEL RVTEMPMOD RES (TC1 = -9.91e-4 TC2 = 1.02e-6)
.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -4.85 VOFF = -1.85)
.MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -1.85 VOFF = -4.85)
.MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -1.35 VOFF = 1.65)
.MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 1.65 VOFF = -1.35)

.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991.



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CROSSVOLT™	GTO™	QFET™	SyncFET™
DenseTrench™	HiSeC™	QS™	TinyLogic™
DOME™	ISOPLANAR™	QT Optoelectronics™	UHC™
EcoSPARK™	LittleFET™	Quiet Series™	UltraFET™
E ² CMOS™	MicroFET™	SILENT SWITCHER [®]	VCX™
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PRODUCT STATUS DEFINITIONS

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Datasheet Identification	Product Status	Definition
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